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General Description

The DS4M125/DS4M133/DS4M200 are margining clock oscillators with LVPECL or LVDS outputs. They are designed to fit in a 5mm x 3.2mm ceramic package with an AT-cut fundamental-mode crystal to form a complete clock oscillator. The circuit can generate the following frequencies and their ±5% frequency deviations: 125MHz, 133.33MHz, and 200MHz. The DS4M125/ DS4M133/DS4M200 employ a low-jitter PLL to generate the frequencies. The typical phase jitter is less than 0.9ps RMS from 12kHz to 20MHz.

Frequency margining is a circuit operation to change the output frequency to 5% higher or 5% lower than the nominal frequency. Frequency margining is accomplished through the margining select pin, MS. This three-state input pin accepts a three-level voltage signal to control the output frequency. In a low-level state, the output frequency is set to the nominal frequency. When set to a high-level state, the frequency output is set to the nominal frequency plus 5%. When set to the midlevel state, the frequency output is equal to the nominal frequency minus 5%. If left open, the MS pin is pulled low by an internal $100k\Omega$ (nominal) pulldown resistor.

The DS4M125/DS4M133/DS4M200 are available with either an LVPECL or LVDS output. The output can be disabled by pulling the OE pin low. When disabled, both OUTP and OUTN levels of the LVPECL driver go to the LVPECL bias voltage, while the output of the LVDS driver is a logical one. The OE input is an active-high logic signal and has an internal $100k\Omega$ pullup resistor. When OE is in a logic-high state, the OUTP and OUTN outputs are enabled.

The devices operate from a single 3.3V supply voltage.

Applications

Memory Clocks **RAID Systems**

Features

- ♦ Frequency Margining: ±5%
- ♦ Nominal Clock Output Frequencies: 125MHz, 133.33MHz, and 200MHz
- ♦ Jitter < 0.9ps RMS from 12kHz to 20MHz
- **♦ LVPECL or LVDS Output**
- ♦ 3.3V Operating Voltage
- ♦ Operating Temperature Range: -40°C to +85°C
- ♦ Supply Current: < 100mA at 3.3V</p>
- **♦ Excellent Power-Supply Noise Rejection**
- ♦ 5mm x 3.2mm Ceramic LCCC Package
- ♦ Output Enable/Disable

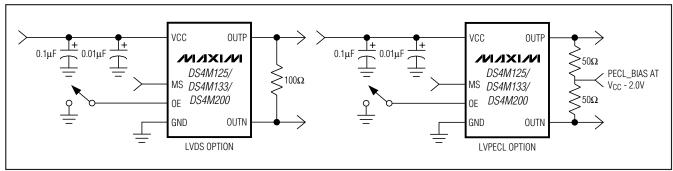
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
DS4M125 P+33	-40°C to +85°C	10 LCCC
DS4M125D+33	-40°C to +85°C	10 LCCC
DS4M133 P+33	-40°C to +85°C	10 LCCC
DS4M133D+33	-40°C to +85°C	10 LCCC
DS4M200 P+33	-40°C to +85°C	10 LCCC
DS4M200D+33	-40°C to +85°C	10 LCCC

⁺Denotes a lead(Pb)-free package. The lead finish is JESD97 category e4 (Au over Ni) and is compatible with both lead-based and lead-free soldering processes.

Pin Configuration and Selector Guide appear at end of data sheet.

Typical Operating Circuit



Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

Power-Supply Voltage Range (VCC)	0.3V to +4.0V
Continuous Power Dissipation (T _A = +70°C)	330mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+125°C

Storage Temperature Range	e55°C to +85°C
Soldering Temperature	
(3 passes max of reflow)	Refer to the
I	PC/JEDEC J-STD-020 Specification.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 3.135V \text{ to } 3.465V, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted.})$ (Notes 1, 2)

PARAMETER		SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Operating Voltage R	ange	Vcc	(Note 1)	3.135	3.3	3.465	V	
		ICC_D	LVDS, output loaded or unloaded		52	75		
Operating Current		ICC_PU	LVPECL, output unloaded		49	70	mA	
		ICC_PI	LVPECL, output loaded		74	100]	
Inactive Current		ICC_OEZ	V _{OE} = V _{IL}		52	85	mA	
OUTPUT FREQUEN	CY SPECIFIC	ATIONS						
]	DS4M125		MS = 0, OE = 1		125			
Frequency	DS4M133	fO	MS = 0, OE = 1		133.33		MHz	
]	DS4M200		MS = 0, OE = 1		200			
Frequency Stability		Δf _{TOTAL} /f _O	Over temperature range, aging, load, supply, and initial tolerance (Note 3)	-50		+50	ppm	
Frequency Stability (Temperature	Over	Δf _{TEMP} /f	V _{CC} = 3.3V	-35		+35	ppm	
Initial Tolerance		Δfinitial/fv	$V_{CC} = 3.3V, T_A = +25^{\circ}C$		±20		ppm	
Frequency Change I	Due to ∆V _{CC}	Δf _{VCC} /f	V _{CC} = 3.3V ±5%	-3		+3	ppm/V	
Frequency Change I Variation	Due to Load	∆f _{LOAD} /f _O	±10% variation in termination resistance		±1		ppm	
Aging (15 Years)		Δfaging		-7		+7	ppm	
Phase Jitter		JRMS	Integrated phase RMS; 12kHz to 80MHz, V _{CC} = 3.3V, T _A = +25°C		< 0.9		ps	
Accumulated Determine Due to Reference Sp			No margin 155.52MHz output		0.6		ps	
			10kHz		12.9			
Accumulated Deterministic Jitter Due to Power-Supply Noise			100kHz (Note 4)		26.3		1	
			200kHz (Note 4)	20.1		ps		
			1MHz (Note 4)		6.4			
Startup Time		tstrt			1.0		ms	
Frequency Switch Ti	me	tswitch			0.5		ms	
Input-Voltage High (DE)	VIH	(Note 5)	0.7 x V _{CC}		Vcc	V	

ELECTRICAL CHARACTERISTICS (continued)

($V_{CC} = 3.135V$ to 3.465V, $T_A = -40$ °C to +85°C, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input-Voltage Low (OE)	VIL	(Note 5)	0		0.3 x V _C C	V
Input-Leakage High (OE)	ILEAKH	OE voltage = VCC	-5		+5	μΑ
Input-Leakage Low (OE)	ILEAKL	OE voltage = GND	-20		-50	μΑ
Input-Leakage High (MS)	ILEAKH	MS voltage = VCC	20		50	μΑ
Input-Leakage Low (MS)	ILEAKL	MS voltage = GND	-5		+5	μΑ
Input Voltage: High Level (MS)	VIH	(Note 5)	0.75 x V _{CC} + 0.15V		V _{CC}	V
Input Voltage: Mid Level (MS)	V _{IM}	(Note 5)	0.25 x V _{CC} + 0.15V		0.75 x V _{CC} - 0.15V	V
Input Voltage: Low Level (MS)	VIL	(Note 5)	0		0.25 x V _{CC} - 0.15V	V
LVDS						
Output High Voltage	VoH	100Ω differential load (Notes 2, 5)			1.475	V
Output Low Voltage	V _{OL}	100Ω differential load (Notes 2, 5)	0.925			V
Differential Output Voltage	V _{OD}	100Ω differential load	250		425	mV
Change in V _{OD} for Complementary States	Δ V _{OD}	100Ω differential load			25	mV
Offset Output Voltage	Vos	100Ω differential load (Note 2)	1.125		1.275	V
Change in VOS for Complementary States	Δ V _{OS}	100Ω differential load			150	mV
Differential Output Impedance	R _{OLVDS}		80		140	Ω
	LVSSLVDSO	OUTN or OUTP shorted to ground and measure the current in the shorting path			40	
Output Current	LLVDSO	OUTN and OUTP shorted together and measure the change in I _{CC}		6.5		mA
Output Rise Time (Differential)	trlvdso	20% to 80%		175		ps
Output Fall Time (Differential)	t _{FLVDSO}	80% to 20%		175		ps
Duty Cycle	DCYCLE_LVDS		45		55	%
Propagation Delay from OE Going LOW to Logical 1 at OUTP	tPA1	(Figure 2)			200	ns
Propagation Delay from OE Going HIGH to Output Active	t _{P1A}	(Figure 2)			200	ns

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 3.135V \text{ to } 3.465V, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted.})$ (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
LVPECL						•
Output High Voltage (Note 2)	VoH	Output connected to 50Ω at PECL_BIAS at V _{CC} - 2.0V	V _{CC} - 1.085		V _{CC} - 0.88	V
Output Low Voltage (Note 2)	V _{OL}	Output connected to 50Ω at PECL_BIAS at V _{CC} - 2.0V	V _{CC} - 1.825		V _{CC} - 1.62	V
Differential Voltage	VDIFF_PECL	Output connected to 50Ω at PECL_BIAS at V _{CC} - 2.0V	0.595	0.710		V
Rise Time	tr-PECL	20% to 80%		200		ps
Fall Time	t _{F-PECL}	80% to 20%		200		ps
Duty Cycle	DCYCLE_PECL		45		55	%
Propagation Delay from OE Going LOW to Output Three-Stated	tpaz	(Figure 3)			200	ns
Propagation Delay from OE Going HIGH to Output Active	tpza	(Figure 3)			200	ns

- Note 1: Limits at -40°C are guaranteed by design and are not production tested. Typical values are at +25°C and 3.3V, unless otherwise noted.
- Note 2: AC parameters are guaranteed by design and characterization and are not production tested.
- Note 3: Frequency stability is calculated as: $\Delta f_{TOTAL} = \Delta f_{INITIAL} + \Delta f_{TEMP} + (\Delta f_{VCC} \times 0.165) + \Delta f_{LOAD} + \Delta f_{AGING}$.
- **Note 4:** Supply induced jitter is measured with a 50mV_{P-P} sine wave forced on V_{CC}. Deterministic jitter is calculated by measuring the power of the resulting tone seen on a spectrum analyzer.
- **Note 5:** Voltage referenced to ground.

SINGLE-SIDEBAND PHASE NOISE AT fo = f_{NOM}

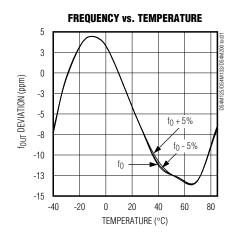
f., _	SINGLE-SIDEBAND PHASE NOISE AT f _O = f _{NOM} (dBc/Hz)				
f _M =	125MHz	133.33MHz	200MHz		
10Hz	-70	-75	-70		
100Hz	-100	-105	-100		
1kHz	-118	-121	-115		
10kHz	-118	-122	-117		
100kHz	-124	-126	-122		
1MHz	-142	-141	-138		
10MHz	-150	-150	-150		
20MHz	-150	-150	-150		

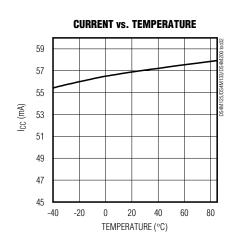
Pin Description

PIN	NAME	FUNCTION
1	OE	Active-High Output Enable. Has an internal pullup 100kΩ resistor.
2	MS	Margin Select. Three-level input with a 100kΩ pulldown resistor.
3	GND	Ground
4	OUTP	Positive Output for LVPECL or LVDS
5	OUTN	Negative Output for LVPECL or LVDS
6	VCC	Supply Voltage
7–10	N.C.	No Connection. Must be floated.
_	EP	Exposed Paddle. The exposed pad must be used for thermal relief. This pad must be connected to ground.

Typical Operating Characteristics

($V_{CC} = +3.3V$, $T_A = +25$ °C, unless otherwise noted.)





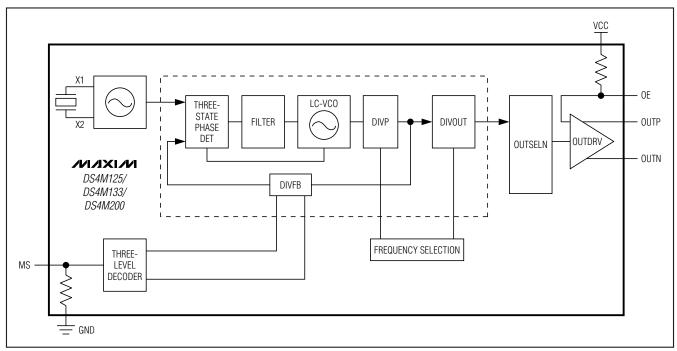


Figure 1. Functional Diagram

Detailed Description

The DS4M125/DS4M133/DS4M200 consist of an oscillator designed to oscillate with a fundamental-mode crystal and a PLL to synthesize the base frequency with its ±5% deviations. The output interface is either LVPECL or LVDS.

The ±5% frequency deviation is controlled through a three-level margining select (MS) pin. This three-state input pin accepts a three-level voltage signal to control the output frequency. In a low-level state, the output frequency is set to the nominal frequency. When set to a high-level state, the frequency output is set to the

The devices are available with either LVDS or LVPECL output drivers. When the OE signal is low, the LVPECL output driver is turned off and the output voltage goes to the PECL_BIAS level of V_{CC} - 2.0V, while the LVDS outputs are a logical one. The OE pin has an internal $100k\Omega$ pullup resistor. When the pin is left floating, the

nominal frequency plus 5%. When set to the mid-level state, the frequency output is equal to the nominal fre-

quency minus 5%. The MS pin has an internal $100k\Omega$

pulldown resistor. When the pin is left floating, the

devices output a nominal frequency.

device output is active.

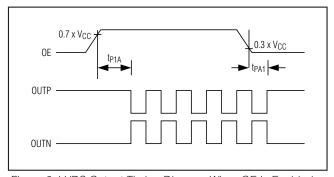


Figure 2. LVDS Output Timing Diagram When OE Is Enabled and Disabled

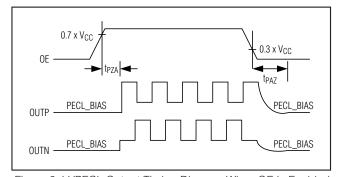


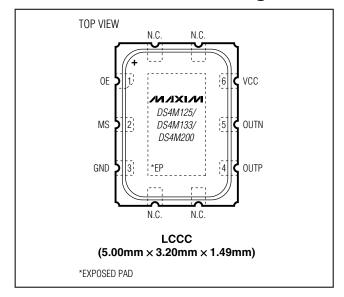
Figure 3. LVPECL Output Timing Diagram When OE Is Enabled and Disabled

Selector Guide

PART	FREQUENCY (NOM) (MHz)	OUTPUT TYPE	TOP MARK
DS4M125 P+33	125	LVPECL	MEP
DS4M125D+33	125	LVDS	MED
DS4M133 P+33	133.33	LVPECL	MFP
DS4M133D+33	133.33	LVDS	MFD
DS4M200 P+33	200	LVPECL	MJP
DS4M200D+33	200	LVDS	MJD

⁺Denotes a lead-free package. The lead finish is JESD97 category e4 (Au over Ni) and is compatible with both lead-based and lead-free soldering processes. A + appears anywhere on the top mark.

Pin Configuration



Chip Information

SUBSTRATE CONNECTED TO GROUND PROCESS: BIPOLAR SIGE

Thermal Information

THETA-JA (°C/W)
90

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
10 LCCC	L1053+H2	<u>21-0389</u>

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